MICROCHIP 24AA64/24LC64/24FC64

64K I²C[™] Serial EEPROM

Device Selection Table

Part Number	Vcc Range	Max. Clock Frequency	Temp. Ranges
24AA64	1.7-5.5	400 kHz ⁽¹⁾	I
24LC64	2.5-5.5	400 kHz	I, E
24FC64	1.7-5.5	1 MHz ⁽²⁾	I

Note 1: 100 kHz for VCC <2.5V **2:** 400 kHz for VCC <2.5V

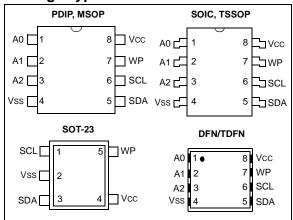
Features:

- Single-Supply with Operation down to 1.7V for 24AA64/24FC64 devices, 2.5V for 24LC64 devices
- Low-Power CMOS Technology:
 - Active current 1 mA, typical
 - Standby current 1 μA, typical
- 2-Wire Serial Interface, I²C[™] Compatible
- · Cascadable up to 8 Devices
- Schmitt Trigger Inputs for Noise Suppression
- Output Slope Control to Eliminate Ground Bounce
- 100 kHz and 400 kHz Clock Compatibility
- 1 MHz Clock for FC versions
- · Page Write Time 5 ms, typical
- Self-timed Erase/Write Cycle
- 32-Byte Page Write Buffer
- Hardware Write-protect
- ESD Protection > 4,000V
- More than 1 Million Erase/Write Cycles
- Data Retention > 200 Years
- Factory Programming Available
- Packages include 8-lead PDIP, SOIC, TSSOP, MSOP, DFN, TDFN and 5-lead SOT-23
- · Pb-Free and RoHS Compliant
- Temperature Ranges:
 - Industrial (I): -40°C to +85°C
 - Automotive (E): -40°C to +125°C

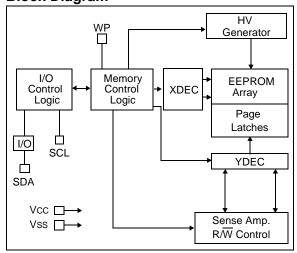
Description:

The Microchip Technology Inc. 24AA64/24LC64/24FC64 (24XX64*) is a 64 Kbit Electrically Erasable PROM. The device is organized as a single block of 8K x 8-bit memory with a 2-wire serial interface. Low-voltage design permits operation down to 1.7V, with standby and active currents of only 1 μ A and 1 mA, respectively. It has been developed for advanced, low-power applications such as personal communications or data acquisition. The 24XX64 also has a page write capability for up to 32 bytes of data. Functional address lines allow up to eight devices on the same bus, for up to 512 Kbits address space. The 24XX64 is available in the standard 8-pin PDIP, surface mount SOIC, TSSOP, DFN, TDFN and MSOP packages. The 24XX64 is also available in the 5-lead SOT-23 package.

Package Types



Block Diagram



^{* 24}XX64 is used in this document as a generic part number for the 24AA64/24LC64/24FC64 devices.

24AA64/24LC64/24FC64

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: DC CHARACTERISTICS

DC CHARACTERISTICS		Industrial (I): TA = -40° C to $+85^{\circ}$ C, VCC = $+1.7$ V to $+5.5$ V Automotive (E): TA = -40° C to $+125^{\circ}$ C, VCC = $+2.5$ V to $+5.5$ V					
Param. No.	Sym Characteristic		Min.	Тур.	Max.	Units	Conditions
	_	A0, A1, A2, WP, SCL and SDA pins	_	_	_	_	_
D1	VIH	High-level input voltage	0.7 Vcc	_	_	V	_
D2	VIL	Low-level input voltage		_	0.3 Vcc 0.2 Vcc	V V	VCC ≥ 2.5V VCC < 2.5V
D3	VHYS	Hysteresis of Schmitt Trigger inputs (SDA, SCL pins)	0.05 Vcc			V	VCC ≥ 2.5V (Note 1)
D4	VOL	Low-level output voltage	_	_	0.40	V	IOL = 3.0 mA @ VCC = 4.5V IOL = 2.1 mA @ VCC = 2.5V
D5	ILI	Input leakage current			±1	μΑ	VIN = VSS or VCC, WP = VSS VIN = VSS or VCC, WP = VCC
D6	ILO	Output leakage current	_	_	±1	μΑ	Vout = Vss or Vcc
D7	CIN, COUT	Pin capacitance (all inputs/outputs)	_	_	10	pF	VCC = 5.0V (Note 1) TA = 25°C, FCLK = 1 MHz
D8	Icc write	Operating current	_	0.1	3	mA	VCC = 5.5V, SCL = 400 kHz
D9	Icc read			0.05	400	μΑ	
D10	Iccs	Standby current		.01 —	1 5	μA μA	Industrial Automotive SDA = SCL = VCC A0, A1, A2, WP = VSS

Note 1: This parameter is periodically sampled and not 100% tested.

^{2:} Typical measurements taken at room temperature.

TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS			Electrical Characteristics: Industrial (I): VCC = +1.7V to 5.5V TA = -40°C to +85°C Automotive (E): VCC = +2.5V to 5.5V TA = -40°C to 125°C				
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions	
1	FCLK	Clock frequency	_ _ _ _	100 400 400 1000	kHz	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5V ≤ VCC ≤ 5.5V 24FC64	
2	THIGH	Clock high time	4000 600 600 500	_ _ _ _	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5V ≤ VCC ≤ 5.5V 24FC64	
3	TLOW	Clock low time	4700 1300 1300 500	_ _ _ _	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5V ≤ VCC ≤ 5.5V 24FC64	
4	TR	SDA and SCL rise time (Note 1)	_ _ _	1000 300 300	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC ≤ 5.5V 24FC64	
5	TF	SDA and SCL fall time (Note 1)	_	300 100	ns	All except, 24FC64 1.7V ≤ VCC ≤ 5.5V 24FC64	
6	THD:STA	Start condition hold time	4000 600 600 250	_ _ _ _	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5V ≤ VCC ≤ 5.5V 24FC64	
7	Tsu:sta	Start condition setup time	4700 600 600 250	_ _ _ _	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5V ≤ VCC ≤ 5.5V 24FC64	
8	THD:DAT	Data input hold time	0	_	ns	(Note 2)	
9	TSU:DAT	Data input setup time	250 100 100	_ _ _	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC ≤ 5.5V 24FC64	
10	Tsu:sto	Stop condition setup time	4000 600 600 250	_ _ _ _	ns	1.7 V ≤ VCC < 2.5V 2.5 V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5 V ≤ VCC ≤ 5.5V 24FC64	
11	Tsu:wp	WP setup time	4000 600 600	_ _ _	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC ≤ 5.5V 24FC64	
12	THD:WP	WP hold time 0% tested, CB = total capacit	4700 1300 1300	_ _ _	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC ≤ 5.5V 24FC64	

Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

- 2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.
- **3:** The combined TsP and VHYS specifications are due to new Schmitt Trigger inputs, which provide improved noise spike suppression. This eliminates the need for a Ti specification for standard operation.
- **4:** This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model, which can be obtained from Microchip's web site

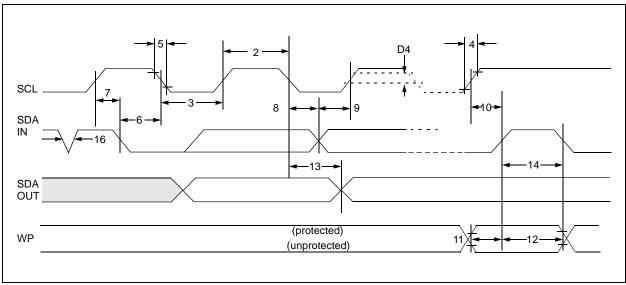
24AA64/24LC64/24FC64

AC CHARACTERISTICS		Electrical Characteristics: Industrial (I): VCC = +1.7V to 5.5V TA = -40°C to +85°C Automotive (E): VCC = +2.5V to 5.5V TA = -40°C to 125°C				
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
13	ТАА	Output valid from clock (Note 2)	_ _ _ _	3500 900 900 400	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5V ≤ VCC ≤ 5.5V 24FC64
14	TBUF	Bus free time: Time the bus must be free before a new transmission can start	4700 1300 1300 500	 	ns	1.7V ≤ VCC < 2.5V 2.5V ≤ VCC ≤ 5.5V 1.7V ≤ VCC < 2.5V 24FC64 2.5V ≤ VCC ≤ 5.5V 24FC64
15	TOF	Output fall time from VIH minimum to VIL maximum CB ≤ 100 pF	10 + 0.1CB	250 250	ns	All except, 24FC64 (Note 1) 24FC64 (Note 1)
16	TSP	Input filter spike suppression (SDA and SCL pins)	_	50	ns	All except, 24FC64 (Notes 1 and 3)
17	Twc	Write cycle time (byte or page)	_	5	ms	_
18	_	Endurance	1,000,000	_	cycles	25°C (Note 4)

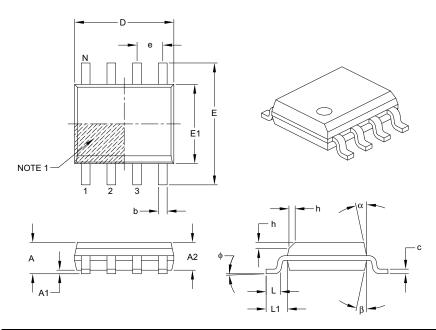
Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

- 2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.
- **3:** The combined TSP and VHYS specifications are due to new Schmitt Trigger inputs, which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.
- **4:** This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model, which can be obtained from Microchip's web site at www.microchip.com.

FIGURE 1-1: BUS TIMING DATA



8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]



	Units	MILLIMETERS			
Dimer	sion Limits	MIN	NOM	MAX	
Number of Pins	N	8			
Pitch	е		1.27 BSC		
Overall Height	Α	-	_	1.75	
Molded Package Thickness	A2	1.25 – –			
Standoff §	A1	0.10 – 0.25			
Overall Width	Е	6.00 BSC			
Molded Package Width	E1	3.90 BSC			
Overall Length	D	4.90 BSC			
Chamfer (optional)	h	0.25 – 0.50			
Foot Length	L	0.40 – 1.27			
Footprint	L1	1.04 REF			
Foot Angle	ф	0°	-	8°	
Lead Thickness	С	0.17	_	0.25	
Lead Width	b	0.31 – 0.51			
Mold Draft Angle Top	α	5° – 15°			
Mold Draft Angle Bottom	5°	_	15°		

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-057B

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. X /XX | Device Temperature Package Range

Device: 24AA64: 1.7V, 64 Kbit I^2C^{TM} Serial EEPROM

24AA64T: 1.7V, 64 Kbit I²C Serial EEPROM

(Tape and Reel)

24LC64: 2.5V, 64 Kbit I²C Serial EEPROM 24LC64T: 2.5V, 64 Kbit I²C Serial EEPROM

(Tape and Reel)

24FC64: 2.5V, 64 Kbit I²C Serial EEPROM

24FC64T: 2.5V, 64 Kbit I²C Serial EEPROM (Tape

and Reel)

Temperature I = -40°C to +85°C Range: E = -40°C to +125°C

Package: P = Plastic DIP (300 mil body), 8-lead

SN = Plastic SOIC (3.90 mm body), 8-lead SM = Plastic SOIC (5.28 mm body), 8-lead ST = Plastic TSSOP (4.4 mm), 8-lead

MS = Plastic Micro Small Outline (MSOP), 8-lead

MC = 2x3 DFN, 8-lead

 $MNY^{(1)}$ = TDFN (2x3x0.75 mm body), 8-lead OT = SOT-23 (Tape and Reel only), 5-lead

Note 1: "Y" indicates a Nickel Palladium Gold (NiPdAu) finish.

Examples:

- a) 24AA64-I/P: Industrial Temperature, 1.7V, PDIP package
- b) 24AA64-I/SN: Industrial Temperature, 1.7V, SOIC package
- c) 24AA64-I/SM: Industrial Temperature, 1.7V, SOIC (5.28 mm) package
- d) 24AA64T-I/ST: Industrial Temperature, 1.7V, TSSOP package, tape and reel
- e) 24LC64-I/P: Industrial Temperature, 2.5V, PDIP package
- f) 24LC64-E/SN: Extended Temperature, 2.5V, SOIC package
- g) 24LC64-E/SM: Extended Temperature, 2.5V, SOIC (5.28 mm) package
- h) 24LC64-I/ST: Industrial Temperature, 2.5V, TSSOP package